

Model HP-155

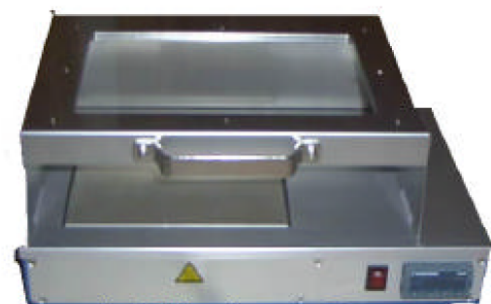
Hot Plate with 155x155mm heated area for up to 150mm wafer



**High precision hot plate with vacuum hold
für up to 6" wafer size or 155x155mm**

- Compact hot plate with integrated precision controller
- Reflow of any soldering alloy
- Pre-heating for wire bonding
- Expoy curing
- Laboratory tests

NEW:
HPP-155
Programmable Hot Plate and
HPP-155-L
with Lift Pins



HP-155: Optional with Cover

Technical Data:

Model	HP-155 Hot Plate
Temperature range	Ambient to 350°C (optional up to 450 °C)
Heated area	155mm x 155mm
Controller	Eurotherm 2132 PID controller with 0,1°C resolution
Power supply	240 V, 1000 Watt (optional: 115 V, 1000 Watt)
Vacuum	Yes
Dimension	320mm x 210mm x 55 mm
Weight	3,5 kg
Controller	Internal PID controller with 0,1° resolution (Eurotherm)

Model NEW !!	HPP-155 Programmable Hot Plate -same as HP-155 but:
Programm	1 program saveable in controller, 16 steps, unlimited program storage on PC using UniSoft Software
RS-232	RS-232 interface
Controller	Eurotherm 2416 PID controller with 0,1°C resolution
Dimension	320mm x 210mm x 85 mm
Option NEW !!	with Lift pins for 1 piece 3" wafer (program controlled (HPP-155-L))
Weight	4,0 kg